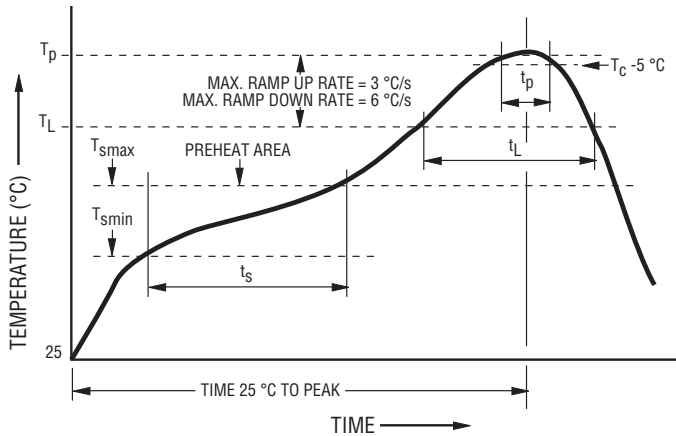


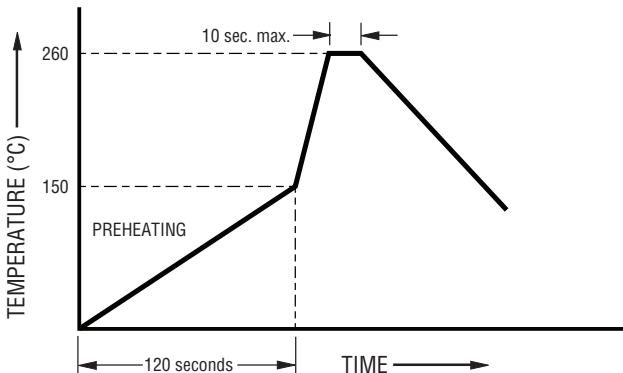
**Solder Reflow Recommendations**



Profile Feature	Pb-Free Assembly
Preheat / Soak: Temperature Min. ( $T_{smin}$ ) Temperature Max. ( $T_{smax}$ ) Time ( $t_s$ ) from ( $T_{smin}$ to $T_{smax}$ )	150 °C 200 °C 60~120 seconds
Ramp Up Rate ( $T_L$ to $T_p$ )	3 °C / second max.
Liquidous Temperature ( $T_L$ ) Time ( $t_L$ ) maintained above $T_L$	217 °C 60~150 seconds
Peak Package Body Temperature ( $T_p$ )	260 °C
Time ( $t_p$ )* within 5 °C of the specified classification temperature ( $T_c$ )	30 seconds*
Ramp Down Rate ( $T_p$ to $T_L$ )	6 °C / second max.
Time 25 °C to Peak Temperature	8 minutes max.

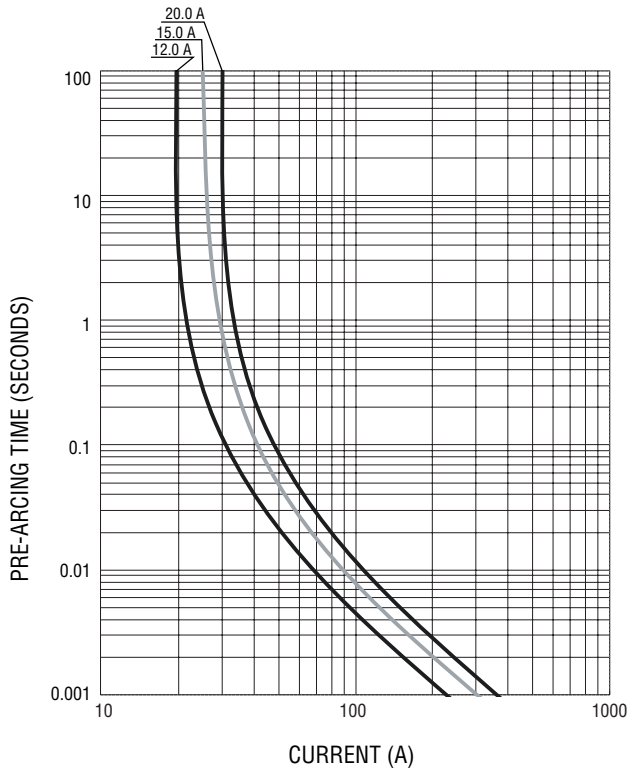
\* Tolerance for peak profile temperature ( $T_p$ ) is defined as a supplier minimum and a user maximum.

**Recommended Temperature Profile for Wave Soldering**



Wave soldering is suitable for 2410 size models.

Average Pre-Arcing Time vs. Current Curves



Average  $I^2t$  vs. t Curves

